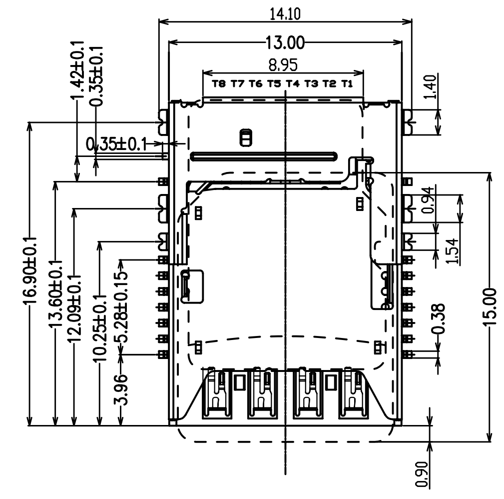
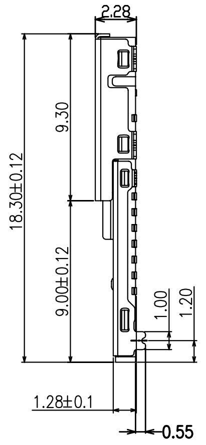
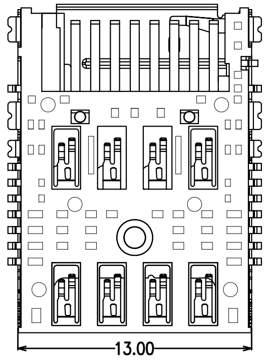
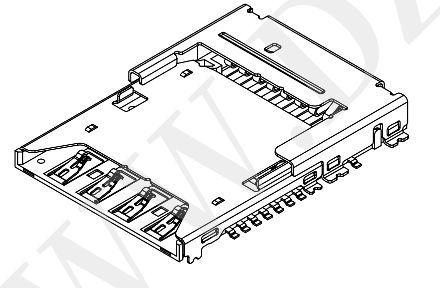
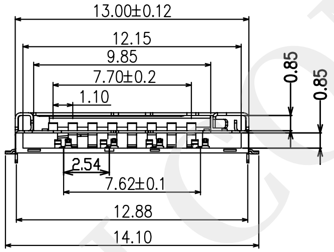
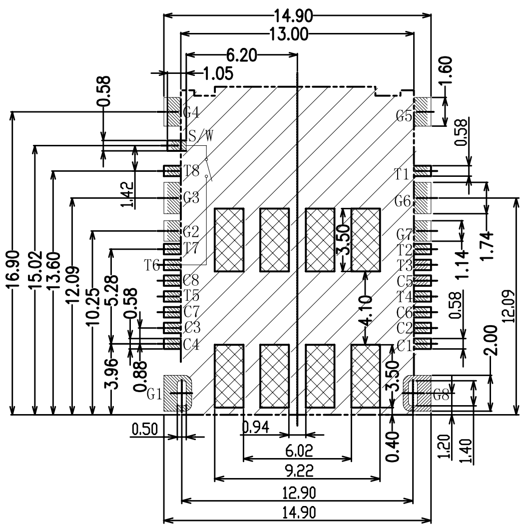












▨ NO PATTERN AREA

▩ NO CIRCUIT AREA

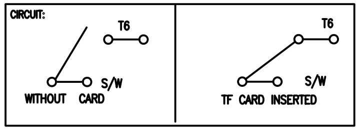
▦ SOLDER AREA

P.C.B LAYOUT

(TOLERANCE±0.05)

TF CARD PIN ASSIGNMENT

PIN NO.	PIN ASSIGNMENT
T1	DAT2
T2	CD/DAT3 ²
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1



SIM pin assignment	
	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

NOTE:

一.材质及电镀方式（MATERIAL AND FINISH）

1.塑胶（HOUSING):LCP,
UL 94V-0 , COLOR:WHITE

2.端子（CONTACT):COPPER ALLOY
GOLD FLASH PLATING ON CONTACT AREA,
GOLD FLASH PLATING ON SOLDER TAILS
50u” NICKEL UNDER PLATING OVER ALL

3.铁壳（SHELL):SUS304-3/4H
40u” NICKEL UNDER PLATING OVER ALL

二.机械特性（MECHANICAL CHARACTERISTICS亐

1.唇 薯ㄗInsertion Force):2.0Kgf Max

2.拔出力 (Withdrawal Force):0.1Kgf Min

3.耐久性(Durability):5000次

三. 电气特性

1.额定电流 (Current rating):1.0A AC/DC

2.接触电阻 (Contact resistance):100mΩ MAX

3.绝缘电阻 (Insulation resistance):500MΩ MIN

4.适用温度 (Operating temperature):-20℃～65℃

华宇创
HOAUC

深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.° ±2° X.X° ±0.5°	**DRAWED BY :** 陈一鸣	**DATE :** 2014-02-23	**PART NAME:** MICRO SIM+TF 同向2IN1卡座 两脚DIP	
	CHECKED BY: 马跃	**DATE :** 2014-02-23	**PART NO.**	HYC43-2IN117-183
UNIT: mm [inch]			**MOLD NO.**	
	APPROVED BY: 邱国夷	**DATE :** 2014-02-23	**DRAW NO:**	HYC-1811223711
SCALE:1:1 **SIZE: A4**			**SHEET NO.**	1 OF 1